1. Objectives

This production information sheet is provided to identify locations of parts, materials, hazardous substances and compound substances in the product that is going to be disposed based on WEEE Directive (2012/19/EU), and to allow waste disposal facilities to dispose the product and to recycle the product in proper manner.

Product: Differential Refractive Index Detector Shodex RI-500 series

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2. Disposal

Information of such product as components, major materials, hazardous substances, etc is listed in the next table.

- ★ In order to promote recycling and other ecological activities, components that can be separated and/or disassembled from the product should be listed in this table. Note that the entry of component weight in the table is not essential. ★
- ★ Fill in the column, Remark with such statements as "Remove oo sheet before disassembly" and "Perform oo processing before disassembly". ★

Component		Major material	Separation	Location where	How to dispose	Weight of	Remark
Category	Sub-category		process is	the material is		component	
			required or	used		(Reference only)	
			not.				
Switching power		Electrolytic	0	Refer to Attached	Shall be disposed		25mm or more
supply unit		capacitor		drawing ①.	in compliance with		
					Directive		
					2008/98/EC		

Component		Major material	Separation	Location where	How to dispose	Weight of	Remark
Category	Sub-category		process is required or	the material is used		component (Reference only)	
		Epoxy glass, and Other electronic component	not.	Refer to Attached drawing ①.	ditto		The printed circuit board is greater than 10 cm ²
		Aluminum, Ferrite, Composite, and Other electronic component	×		Shall be disposed in landfill after the removal from the body		
Operation unit	LCD unit	Liquid crystal material	0	Refer to Attached drawing ②.	Shall be disposed in compliance with Directive 2008/98/EC		LCD whose surface area is larger than 100cm ²
	Circuit board	Epoxy glass, and Other electronic component	0	Refer to Attached drawing ③.	ditto		The printed circuit board is greater than 10 cm ²
Keyboard		Epoxy glass Other electronic component	0	Refer to Attached drawing ④.	ditto		ditto

Component		Major material	Separation	Location where	How to dispose	Weight of	Remark
Category	Sub-category	1	process is	the material is		component	
			required or	used		(Reference only)	
			not.				
Cover		Iron	×		Material recycle		Shall be separated
							from other parts
Chassis		Stainless	×		ditto		ditto
Plastic panel	Front Panel Cover	PBT (Polybutylene	0	Refer to Attached	Shall be disposed		Plastic containing
		Terephthalate)		drawings ⑤ and	in compliance with		brominated flame
	Joint Panel Cover			6.	Directive		retardants.
					2008/98/EC		
Optical unit	Optical block	Aluminum	×	Refer to Attached	Material recycle		Shall remove all of
				drawing ⑦.			the mounted
							components
	Optical unit cover	Stainless	×		ditto		ditto
	Plastic foam		×		Thermal recycle		
	insulating material						

Component		Major material	Separation	Location where	How to dispose	Weight of	Remark
Category	Sub-category		process is required or	the material is used		component (Reference only)	
Measurement		Epoxy glass	not.	Refer to Attached	Shall be disposed		The printed circuit
Board		Other electronic		drawing 8.	in compliance with		
board				drawing .			board is greater
		component			Directive		than 10 cm ²
					2008/98/EC		
I/V Circuit Board		Epoxy glass	0	Refer to Attached	ditto		ditto
		Other electronic		drawing ⑦.			
		component					
Power cable		Copper	0	Refer to Attached	Shall be disposed		External electric
		PVC		drawings 9and	in compliance with		cables.
				10.	Directive		
Signal cable					2008/98/EC		
Other removable		Stainless, Optical	×		Shall be disposed		
parts		glass, Epoxy			in landfill after the		
		glass, and			removal from the		
		Electronic			body		
		component					
		Component					

¹⁾ The symbol, "O" used in the column "Separation process is required or not" indicates that the part shall be subjected to the process stipulated in WEEE Directive (2012/19/EU) Annex VII. The symbol, "×" is to show that the part shall be subjected to the separation process.

2) Location of each component is indicated in Attached drawing-1.

3) Remark

• Part to be processed in accordance with WEEE Annex VII Article 8 (2) is indicated in this Remark column.

3. Record and Report

The followings shall be recorded after receiving and disposing our waste product. In addition, contents of the record shall be reported once a year.

- · Number of received waste product and of disposed product
- · Client of disposal (Who asked to dispose the product)
- · Type/Kind of waste product

★ Attach drawing and/or photo showing locations where component and/or hazardous substances are used. ★

